

Vishay General Semiconductor

Surface Mount TRANSZORB® Transient Voltage Suppressors



PRIMARY CHARACTERISTICS					
V _{WM} 5.0 V					
P _{PPM}	100 W				
I _{FSM}	25 A				
T _J max. 150 °C					

TYPICAL APPLICATIONS

Use in sensitive electronics protection against voltage transients induced by inductive load switching and lighting on ICs. MOSFET, signal lines of sensor units specifically for protecting 5.0 V supplied sensitive equipment against transient overvoltages.

FEATURES

Very low profile - typical height of 0.65 mm



HALOGEN

FREE

· Ideal for automated placement

Oxide planar chip junction

Uni-directional polarity only

Peak pulse power: 100 W (10/1000 μs)

AUTOMOTIVE

ESD capability: 15 kV (air), 8 kV (contact)

Meets MSL level 1, per J-STD-020C, LF maximum peak of 260 °C

Solder dip 265 °C max. 10 s, per JESD 22-A111

AEC-Q101 qualified

· Compliant to RoHS directive 2002/95/EC and in accordance to WEEE 2002/96/EC

 Halogen-free according to IEC 61249-2-21 definition

Find out more about Vishay's Automotive Grade Product requirements at: www.vishay.com/applications

MECHANICAL DATA

Case: MicroSMP

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free and RoHS compliant, commercial grade

Base P/NHM3 - halogen-free and RoHS compliant,

automotive grade

Terminals: Matte tin plated leads, solderable per

J-STD-002 and JESD 22-B102

M3 suffix meets JESD 201 class 1A whisker test, HM3

suffix meets JESD 201 class 2 whisker test

Polarity: Color band denotes the cathode end

MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted)						
PARAMETER	SYMBOL	VALUE	UNIT			
Peak pulse power dissipation (1)(2)	P _{PPM}	100	W			
Peak pulse current with a 10/1000 μs waveform (fig. 1)	I _{PPM}	10.9	Α			
Non repetitive peak forward surge current 10 ms single half sine-wave (2)	I _{FSM}	25	Α			
Power dissipation T _L = 120 °C ⁽²⁾	P _D	1.0	W			
Operating junction and storage temperature range	T _J , T _{STG}	- 55 to + 150	°C			

(1) Non-repetitive current pulse, per fig. 1

⁽²⁾ Mounted on 6.0 mm x 6.0 mm copper pads to each terminal

MSP5.0A

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ELECTRICAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)										
DEVICE TYPE	DEVICE MARKING CODE	BREAK VOLT V _{BR} A (\ MIN.	TAGE T I _T ⁽¹⁾	TEST CURRENT I _T (mA)	STAND-OFF VOLTAGE V _{WM} (V)	MAXIMUM REVERSE LEAKAGE AT V _{WM} I _D (μA)	V _C (V) A	_	_	IPING AGE ⁽²⁾ I _{PPM} (A)
MSP5.0A	AE	6.40	7.07	10	5.0	100	9.2	10.9	14.5	57

Notes

⁽¹⁾ Pulse test: $t_p \le 50$ ms (2) Surge current waveform per Fig. 1 and derate per Fig. 2

THERMAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)						
PARAMETER	SYMBOL	VALUE	UNIT			
Typical thermal resistance ⁽¹⁾	$egin{array}{c} R_{ hetaJA} \ R_{ hetaJL} \end{array}$	125 30	°C/W			

IMMUNITY TO STATIC ELECTRICAL DISCHARGE TO THE FOLLOWING STANDARDS (T _A = 25 $^{\circ}$ C unless otherwise noted)							
STANDARD	TEST TYPE	CLASS	VALUE				
AEC-Q101-001	Human body model (contact mode)	C = 100 pF, R = 1.5 kΩ	V	НЗВ	> 8 kV		
IEC-61000-4-2 (2)	Human body model (air discharge mode) (1)	C = 150 pF, R = 150 Ω	V _C	4	> 15 kV		

ORDERING INFORMATION (Example)							
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE			
MSP5.0A-E3/89A	0.006	89A	4500	7" diameter plastic tape and reel			
MSP5.0AHE3/89A (1)	0.006	89A	4500	7" diameter plastic tape and reel			
MSP5.0A-M3/89A	0.006	89A	4500	7" diameter plastic tape and reel			
MSP5.0AHM3/89A (1)	0.006	89A	4500	7" diameter plastic tape and reel			

Note

(1) Automotive grade

Note
(1) Thermal resistance from junction to ambient and junction to lead mounted on P.C.B. with 6.0 mm x 6.0 mm copper pad areas. R_{BJL} is measured

 $^{^{(1)}}$ Immunity to IEC-61000-4-2 air discharge mode has a typical performance > 30 kV $^{(2)}$ System ESD standard



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RATINGS AND CHARACTERISTICS CURVES

(T_A = 25 °C unless otherwise noted)

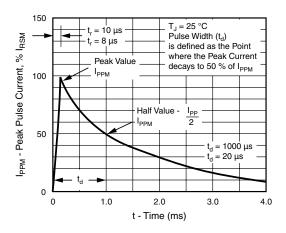


Figure 1. Pulse Waveform

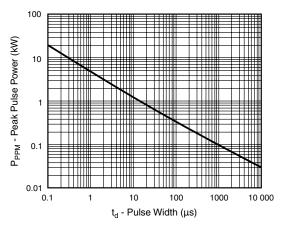


Figure 2. Peak Pulse Power Rating Curve

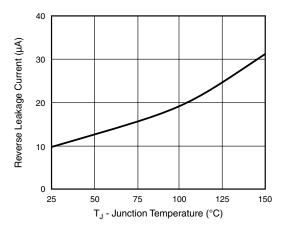


Figure 3. Relative Variation of Leakage Current vs. Junction Temperature

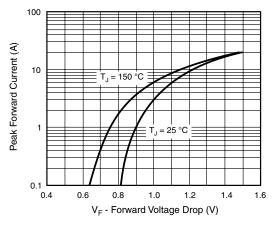


Figure 4. Typical Peak Forward Voltage Drop vs.

Peak Forward Current

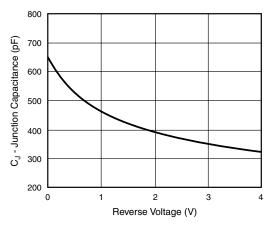


Figure 5. Typical Junction Capacitance

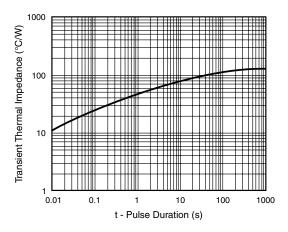


Figure 6. Typical Transient Thermal Impedance

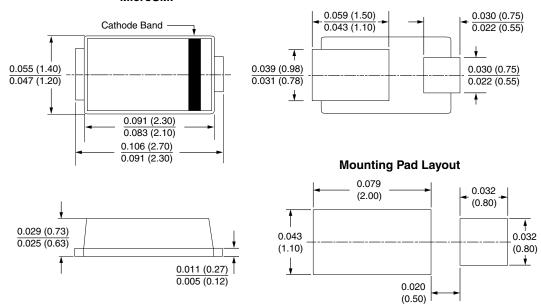
MSP5.0A

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PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

MicroSMP





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